

**ORDERING INFORMATION**

TEMP. RANGE	PACKAGE	PART NUMBER
-40 °C to 85 °C	miniQFN-10	DG2730DN-T1-GE4

**TRUTH TABLE**

$\overline{OE}$ (PIN 8)	S (PIN 10)	FUNCTION
0	1	D+ = HSD1+ and D- = HSD1-
0	0	D+ = HSD2+ and D- = HSD2-
1	X	Disconnect

**PIN DESCRIPTIONS**

PIN NAME	DESCRIPTION
$\overline{OE}$	Bus switch enable
S	Select input
HSD1 $\pm$ , HSD2 $\pm$ , D $\pm$	Data port

**ABSOLUTE MAXIMUM RATINGS** ( $T_A = 25\text{ °C}$ , unless otherwise noted)

PARAMETER		LIMIT	UNIT
Reference to GND	V+	-0.3 to 6	V
	S, $\overline{OE}$ , D $\pm$ , HSD1 $\pm$ , HSD2 $\pm$ <sup>a</sup>	-0.3 to (V+ + 0.3)	
Current (Any Terminal Except S, $\overline{OE}$ , D $\pm$ , HSD1 $\pm$ , HSD2 $\pm$ )		30	mA
Continuous Current (S, $\overline{OE}$ , D $\pm$ , HSD1 $\pm$ , HSD2 $\pm$ )		$\pm 250$	
Peak Current (Pulsed at 1 ms, 10 % duty cycle)		$\pm 500$	
Storage Temperature (D suffix)		-65 to +150	°C
Power Dissipation (Packages) <sup>b</sup>	miniQFN-10 <sup>c</sup>	208	mW
ESD (Human body model)		5.5	kV
Latch-Up (Current injection)		500	mA

**Notes**

- Signals on S,  $\overline{OE}$ , D $\pm$ , HSD1 $\pm$ , HSD2 $\pm$  exceeding V+ will be clamped by internal diodes. Limit forward diode current to maximum current ratings.
- All leads welded or soldered to PC board.
- Derate 2.6 mW/°C above 70 °C.

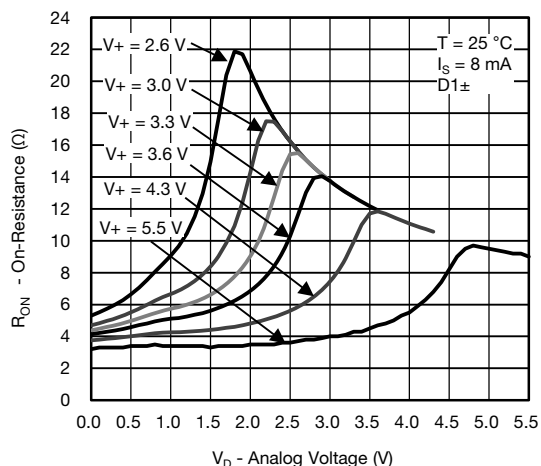
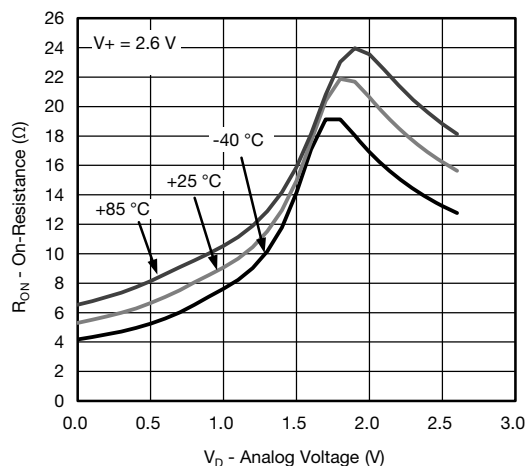
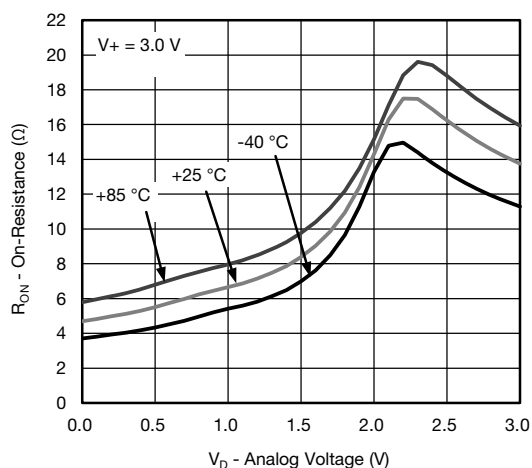
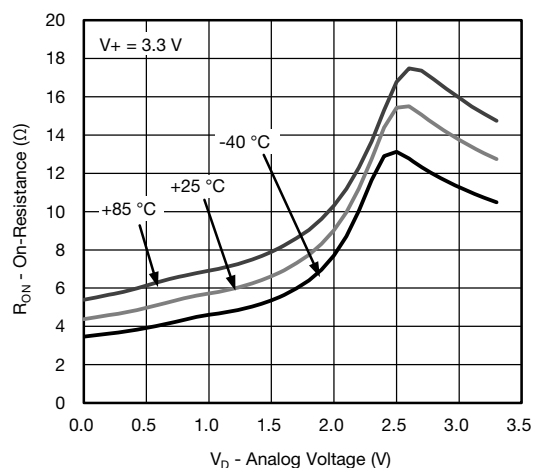
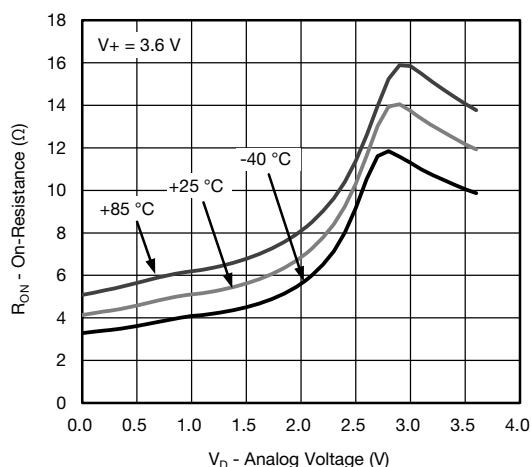
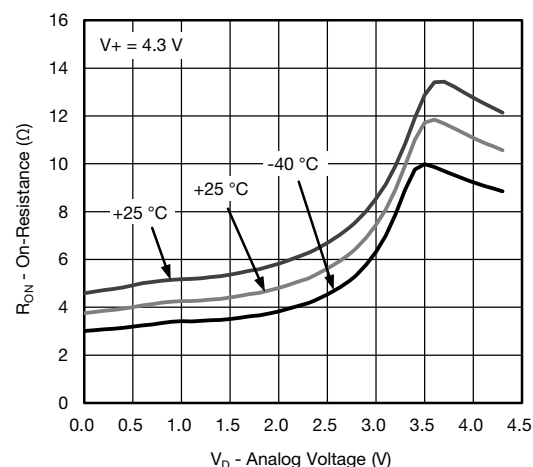
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

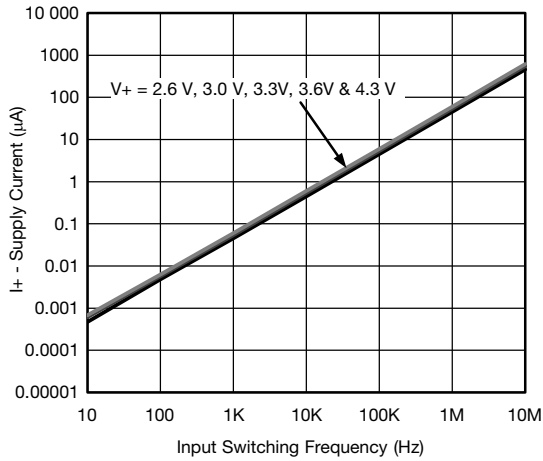
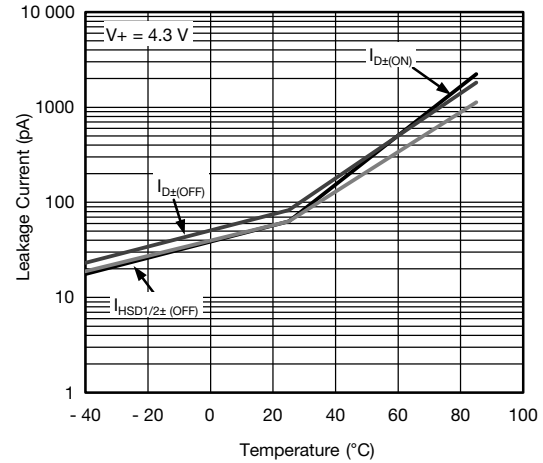
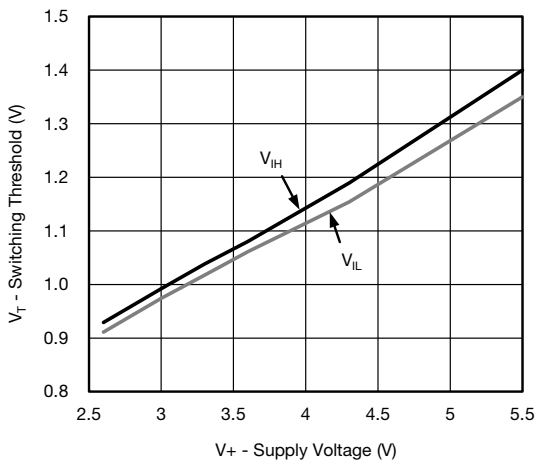
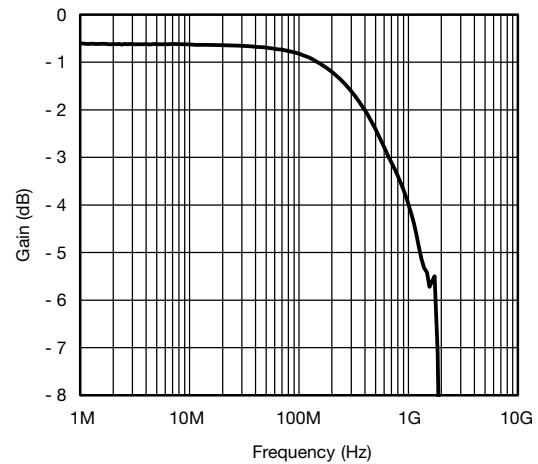
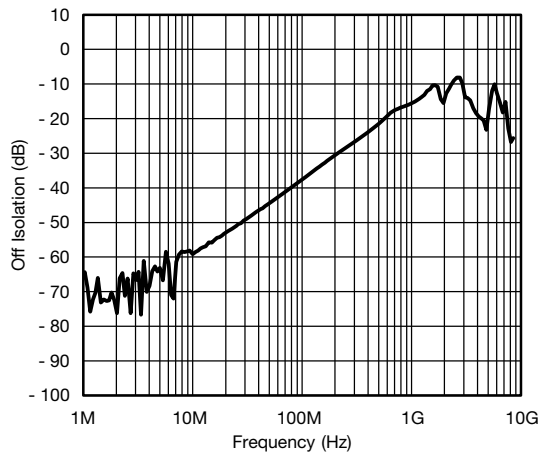
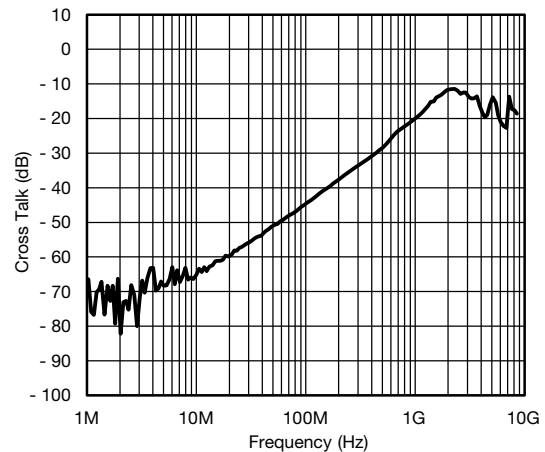


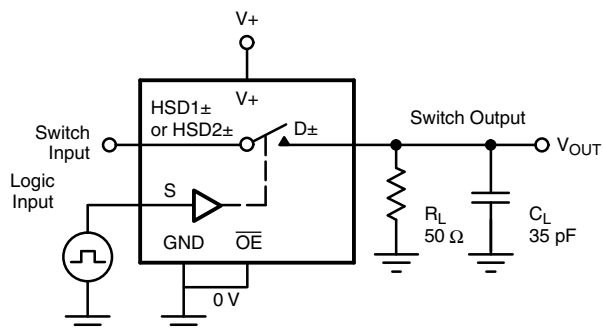
SPECIFICATIONS (V+ = 3 V)							
PARAMETER	SYMBOL	TEST CONDITIONS OTHERWISE UNLESS SPECIFIED	TEMP. <sup>a</sup>	LIMITS -40 °C to +85 °C			UNIT
				MIN. <sup>b</sup>	TYP. <sup>c</sup>	MAX. <sup>b</sup>	
Analog Switch							
Analog Signal Range <sup>d</sup>	V <sub>ANALOG</sub>	R <sub>DS(on)</sub>	Full	0	-	V+	V
On-Resistance	R <sub>DS(on)</sub>	V+ = 3 V, I <sub>D±</sub> = 8 mA, V <sub>HSD1/2±</sub> = 0.4 V	Room	-	5.5	8	Ω
			Full	-	-	9	
On-Resistance Match <sup>d</sup>	ΔR <sub>ON</sub>	V+ = 3 V, I <sub>D±</sub> = 8 mA, V <sub>HSD1/2±</sub> = 0.4 V	Room	-	0.8	-	
On-Resistance Flatness <sup>d</sup>	R <sub>ON</sub> Flatness	V+ = 3 V, I <sub>D±</sub> = 8 mA, V <sub>HSD1/2±</sub> = 0 V, 1 V	Room	-	2	-	
Switch Off Leakage Current	I <sub>off</sub>	V+ = 4.3 V, V <sub>HSD1/2±</sub> = 0.3 V, 3 V, V <sub>D±</sub> = 3 V, 0.3 V	Full	-100	-	100	nA
Channel On Leakage Current	I <sub>on</sub>	V+ = 4.3 V, V <sub>HSD1/2±</sub> = 0.3 V, 4 V, V <sub>D±</sub> = 4 V, 0.3 V	Full	-200	-	200	
Digital Control							
Input Voltage High	V <sub>INH</sub>	V+ = 3 V to 3.6 V	Full	1.3	-	-	V
		V+ = 4.3 V	Full	1.5	-	-	
Input Voltage Low	V <sub>INL</sub>	V+ = 3 V to 4.3 V	Full	-	-	0.5	
Input Capacitance	C <sub>IN</sub>		Full	-	6.5	-	pF
Input Current	I <sub>INL</sub> or I <sub>INH</sub>	V <sub>IN</sub> = 0 or V+	Full	-1	-	1	μA
Dynamic Characteristics							
Break-Before-Make Time <sup>d</sup>	t <sub>BBM</sub>	V+ = 3 V, V <sub>D1/2 ±</sub> = 1.5 V, R <sub>L</sub> = 50 Ω, C <sub>L</sub> = 35 pF	Room	-	5	-	ns
			Full	-	5	-	
S, $\overline{\text{OE}}$ Turn-On Time <sup>d</sup>	t <sub>ON</sub>		Room	-	-	30	
			Full	-	-	30	
S, $\overline{\text{OE}}$ Turn-Off Time <sup>d</sup>	t <sub>OFF</sub>		Room	-	-	25	
			Full	-	-	25	
Charge Injection <sup>d</sup>	Q <sub>INJ</sub>	C <sub>L</sub> = 1 nF, R <sub>GEN</sub> = 0 Ω, V <sub>GEN</sub> = 0 V	Room	-	3	-	pC
Off-Isolation <sup>d</sup>	OIRR	V+ = 3 V to 3.6 V, R <sub>L</sub> = 50 Ω, C <sub>L</sub> = 5 pF, f = 240 MHz		-	-29	-	dB
Crosstalk <sup>d, e</sup>	X <sub>TALK</sub>			-	-36	-	
Bandwidth <sup>d</sup>	BW	V+ = 3 V to 3.6 V, R <sub>L</sub> = 50 Ω, - 3 dB		-	900	-	MHz
D+/D- On Capacitance	C <sub>ON</sub>	V+ = 3.3 V, $\overline{\text{OE}}$ = 0 V, f = 240 MHz		-	5.8	-	pF
D1n, D2n Off Capacitance	C <sub>OFF</sub>	V+ = $\overline{\text{OE}}$ = 3.3 V, f = 240 MHz		-	2.2	-	
Channel-to-Channel Skew <sup>d</sup>	t <sub>SK(O)</sub>	V+ = 3 V to 3.6 V, R <sub>L</sub> = 50 Ω, C <sub>L</sub> = 5 pF		-	50	-	ps
Skew Off Opposite Transitions of the Same Output <sup>d</sup>	t <sub>SK(p)</sub>			-	20	-	
Total Jitter <sup>d</sup>	t <sub>J</sub>			-	200	-	
Power Supply							
Power Supply Range	V+		-	2.6	-	5.5	V
Power Supply Current	I+	V <sub>IN</sub> = 0 V, or V+	Full	-	-	2	μA

**Notes**

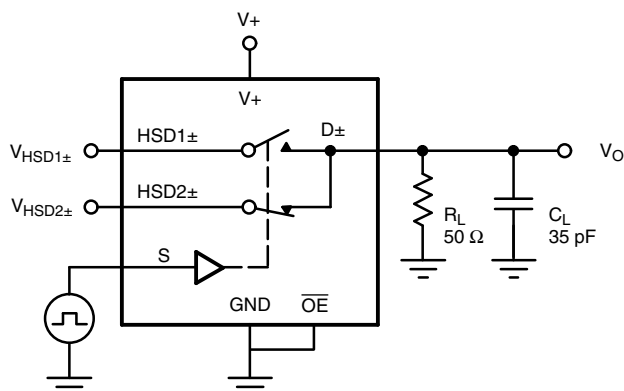
- a. Room = 25 °C, Full = as determined by the operating suffix.  
b. The algebraic convention whereby the most negative value is a minimum and the most positive a maximum, is used in this datasheet.  
c. Typical values are for design aid only, not guaranteed nor subject to production testing.  
d. Guaranteed by design, not subjected to production test.  
e. Crosstalk measured between channels.

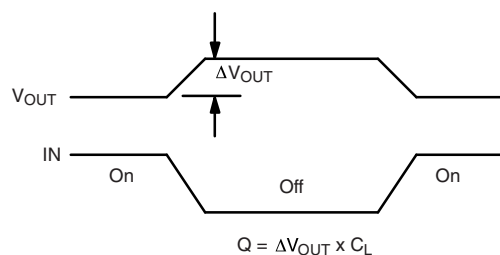
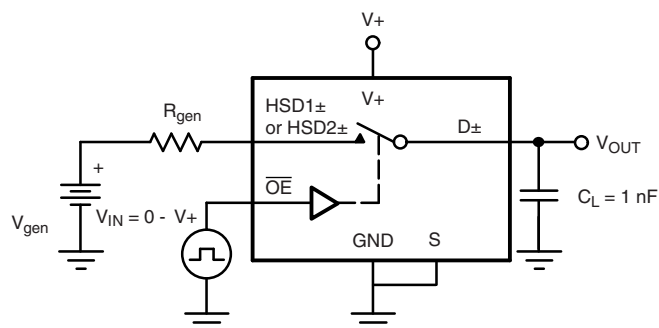
**TYPICAL CHARACTERISTICS** ( $T_A = 25\text{ }^{\circ}\text{C}$ , unless otherwise noted)

 **$R_{ON}$  vs.  $V_D$  and Single Supply Voltage**

 **$R_{ON}$  vs. Analog Voltage and Temperature**

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 **$R_{ON}$  vs. Analog Voltage and Temperature**

**TYPICAL CHARACTERISTICS** ( $T_A = 25^\circ\text{C}$ , unless otherwise noted)

**Supply Current vs. Input Switching Frequency**

**Leakage Current vs. Temperature**

**Switching Threshold vs. Supply Voltage**

**Gain vs. Frequency,  $V_{+} = 3.3\text{ V}$** 

**Off-Isolation,  $V_{+} = 3.3\text{ V}$** 

**Crosstalk,  $V_{+} = 3.3\text{ V}$**

**TEST CIRCUITS**

 $C_L$  (includes fixture and stray capacitance)

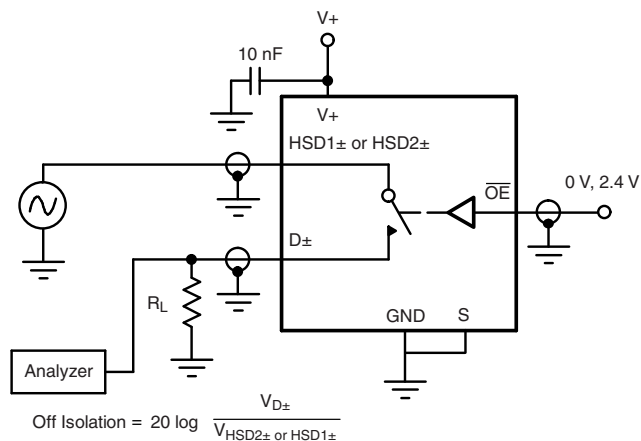
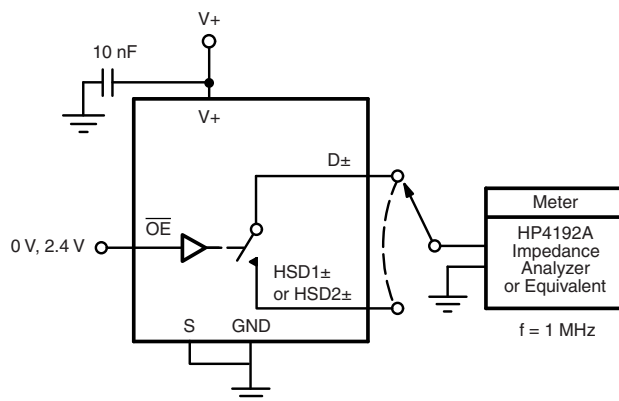
$$V_{OUT} = D_{\pm} \left( \frac{R_L}{R_L + R_{ON}} \right)$$

**Fig. 1 - Switching Time**

 $C_L$  (includes fixture and stray capacitance)

**Fig. 2 - Break-Before-Make Interval**


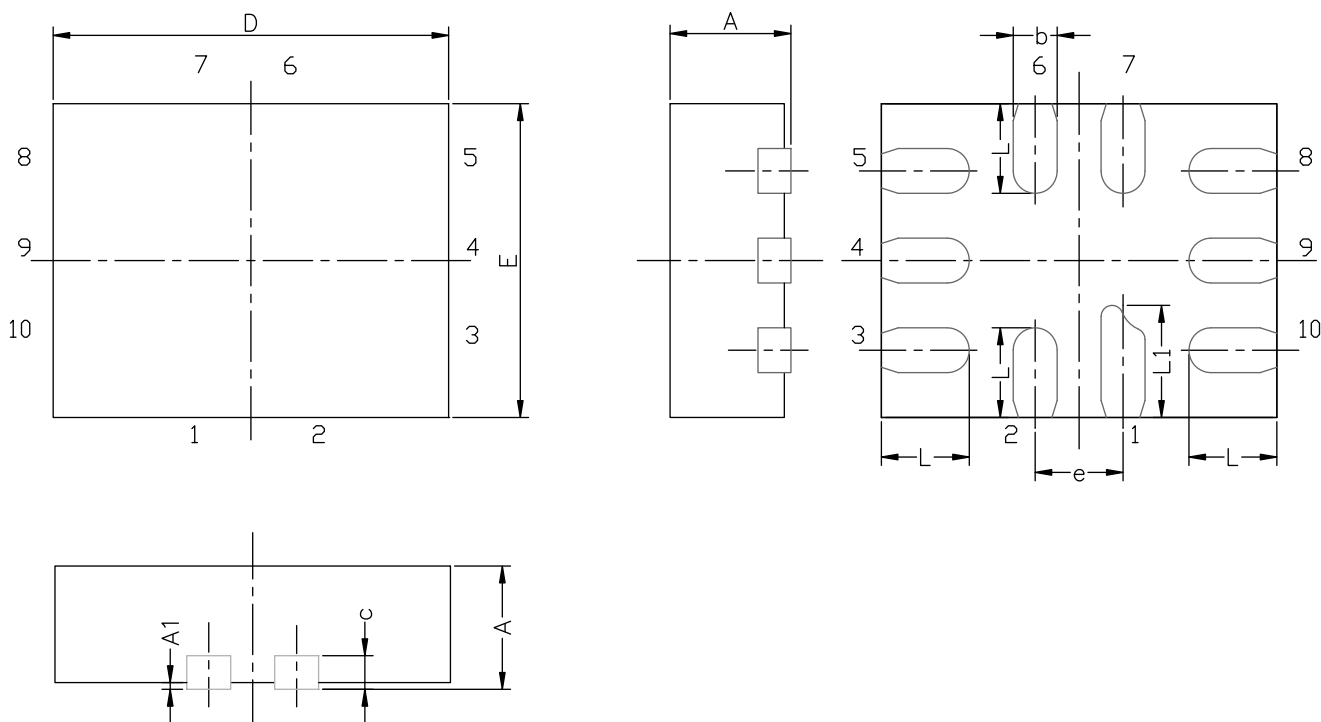
IN depends on switch configuration: input polarity determined by sense of switch.

**Fig. 3 - Charge Injection**

**TEST CIRCUITS**

**Fig. 4 - Off-Isolation**

**Fig. 5 - Channel Off/On Capacitance**

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## MINI QFN-10L CASE OUTLINE



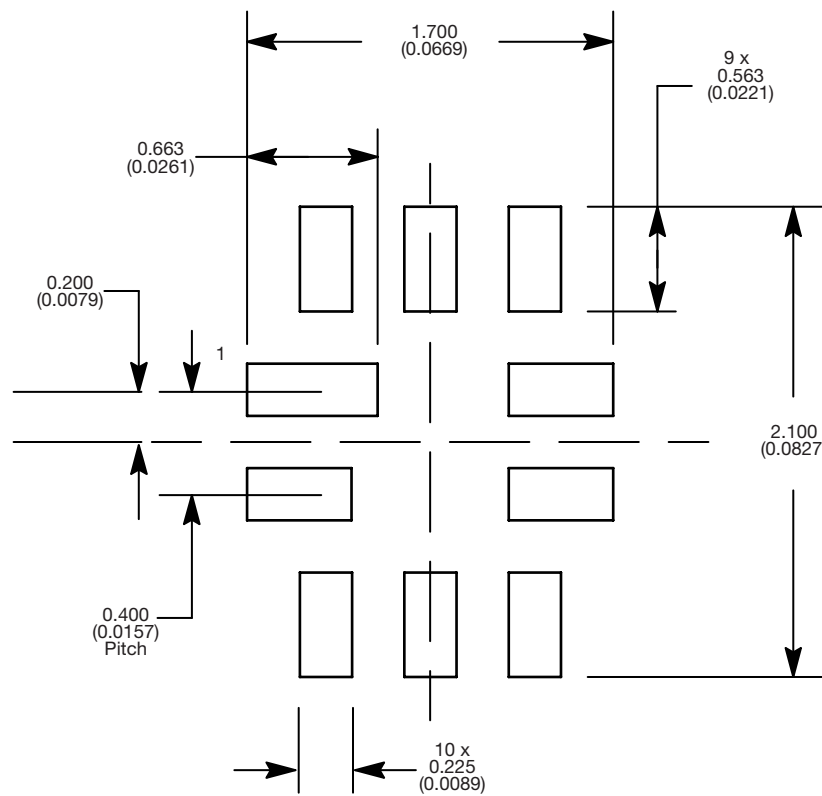
DIM	MILLIMETERS			INCHES		
	MIN.	NAM.	MAX.	MIN.	NAM.	MAX.
A	0.45	0.55	0.60	0.0177	0.0217	0.0236
A1	0.00	-	0.05	0.000	-	0.002
b	0.15	0.20	0.25	0.006	0.008	0.010
c	0.150 or 0.127 REF <sup>(1)</sup>			0.006 or 0.005 REF <sup>(1)</sup>		
D	1.70	1.80	1.90	0.067	0.071	0.075
E	1.30	1.40	1.50	0.051	0.055	0.059
e	0.40 BSC			0.016 BSC		
L	0.35	0.40	0.45	0.014	0.016	0.018
L1	0.45	0.50	0.55	0.0177	0.0197	0.0217

### Note

<sup>(1)</sup> The dimension depends on the leadframe that assembly house used.

ECN T16-0163-Rev. B, 16-May-16  
DWG: 5957

## RECOMMENDED MINIMUM PADS FOR MINI QFN 10L



Mounting Footprint  
Dimensions in mm (inch)





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